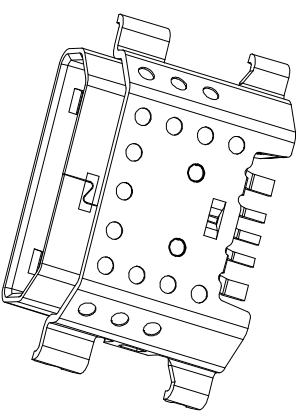
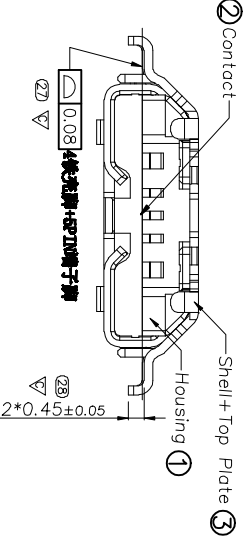
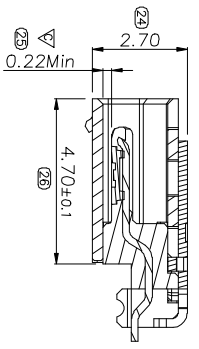
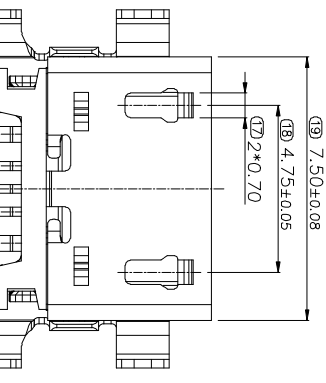


RECOMMENDED PCB LAYOUT
TOP VIEW (TOLERANCE: ±0.05)

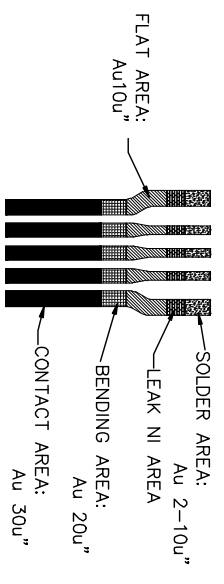


3D VIEW



NOTE:

- 1.MATERIAL:
- 1.1.HOUSING MATERIAL: LCP E130I, COLOR: BLACK;
- 1.2.CONTACT PLATING: NICKEL AND COPPER C7025-TM03; PLATING:NICKEL 120~200u" UNDER PLATED OVER ALL; GOLD PLATING INSTRUCTIONS;



- 1.3.SHELL MATERIAL : STAINLESS STEEL SUS 301-1/2H, SHELL PLATING: NI 50u" Min UNDER PLATED OVER ALL
- 1.4.TOP PLATE MATERIAL: STAINLESS STEEL SUS 301-3/4H, TOP PLATE PLATING : NI 60u" Min UNDER PLATED OVER ALL, AU 2U"MIN PLATED AT SOLDER TAIL AREA
- 2.PERFORMANCE:
- 2.1.Applied AC 100V for 1 minute t_{MA}
- 2.2.CONTACT RESISTANCE: 30m Ω Max INITIAL, 40mΩ Max. FINAL,
- 2.3.INSULATION RESISTANCE: 1000MOHM Min.
- 2.4.MATING AND UNMATING FORCE:
- 2.5.DURABILITY : 10000 CYCLES
- 3.MARK ∇ THE KEY SIZE, MARK ⊕ FAI.

④	TOP PLATE	3.062SE-000-1R6
③	SHELL	3.062SD-000-NR6
②	CONTACT	3.06214-005-7R7
①	HOUSING	3.062M5-005-7R1
ITEM	PART NAME	PART No.

EXTEND USE		TITLE	
MICRO USB 5P	UNIT mm	MICRO USB 5P	CUST'DWG
GENERAL TOLERANCE ⑥		APPD Lihong Tan 04/12-17	
DIMENSION ANGLES ±.3°		CHD John Wang 04/12-17	
.0 ±0.30		FINISHED QTY	
.0 ±0.20		P/N:	
.00 ±0.10		3.062AC-005-7R0	
.00 ±0.05		SHEET SCALE 1:1	
		REV B	



REV	ECN NO	DESCRIPTION	DATE	APPD
A		轉產, 正式圖發行	2017.02.14	Quantong Wang
B	FEIN1704005	根據客戶ICT170005修改機械力標注	2017.04.12	Quantong Wang